![Texas Instruments logo] **TEXAS INSTRUMENTS**
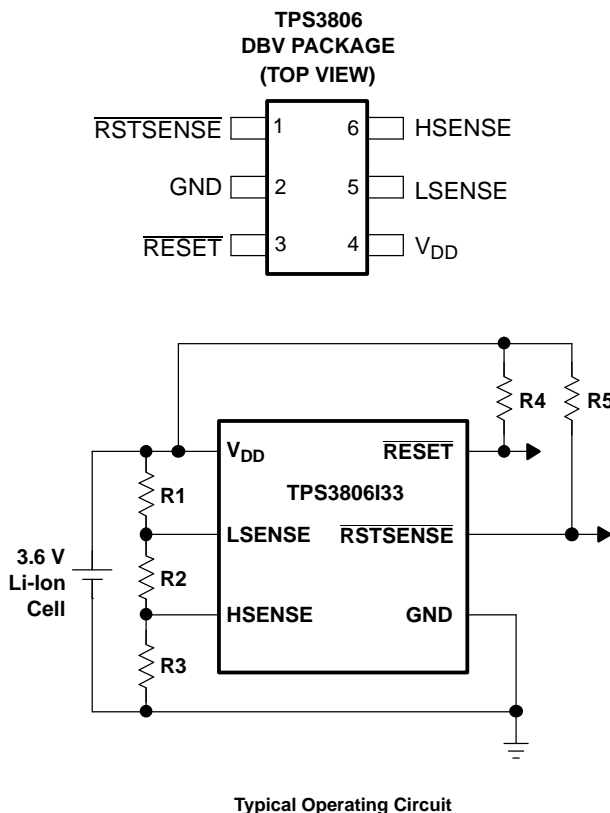www.ti.com

Dual Voltage Detector with Adjustable Hysteresis

FEATURES

- **Dual Voltage Detector With Adjustable Hysteresis 3.3-V/Adjustable and 2-V/Adjustable**
- **Assured Reset at V_{DD} = 0.8 V**
- **Supply Current: 3 µA Typical at V_{DD} = 3.3 V**
- **Independent Open-Drain Reset Outputs**
- **Temperature Range: -40°C to +85°C**
- **6-Pin SOT-23 Package**

DESCRIPTION

The TPS3806 integrates two independent voltage detectors for battery voltage monitoring. During power-on, $\overline{RESET}$ and $\overline{RSTSENSE}$ are asserted when supply voltage V_{DD} or the voltage at LSENSE input become higher than 0.8 V. Thereafter, the supervisory circuit monitors V_{DD} and LSENSE, keeping $\overline{RESET}$ and $\overline{RSTSENSE}$ active as long as V_{DD} and LSENSE remain below the threshold voltage, V_{IT}. As soon as V_{DD} or LSENSE rise above the threshold voltage V_{IT}, $\overline{RESET}$ or $\overline{RSTSENSE}$ is deasserted, respectively. The TPS3806 device has a fixed-sense threshold voltage V_{IT} set by an internal voltage divider at V_{DD} and an adjustable second-LSENSE input. In addition, an upper voltage threshold can be set at HSENSE to allow a wide adjustable hysteresis window.

The devices are available in a 6-pin SOT-23 package. The TPS3806 device is characterized for operation over a temperature range of -40°C to +85°C.

**TPS3806
DBV PACKAGE
(TOP VIEW)**

Typical Operating Circuit

TPS3806J20
TPS3806I33
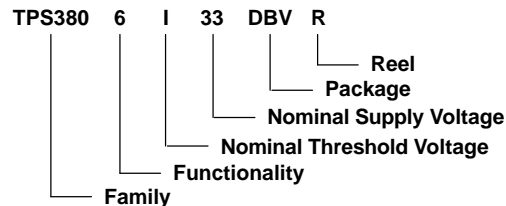
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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

ORDERING INFORMATION[1]

T$_A$	DEVICE NAME		THRESHOLD VOLTAGE		MARKING
			V$_{DD}$	SENSE	
-40°C to +85°C	TPS3806J20DBVR[2]	TPS3806J20DBVT[3]	1.8 V	1.207 V	PGQI
	TPS3806I33DBVR[2]	TPS3806I33DBVT[3]	3 V	1.207 V	PGPI

(1) For the most current package and ordering information, see the Package Option Addendum located at the end of this data sheet or refer to our web site at www.ti.com.
(2) The DBV**R** passive indicates tape and reel containing 3000 parts.
(3) The DBV**T** passive indicates tape and reel containing 250 parts.

```
TPS380   6   I   33   DBV   R
                              └──── Reel
                        └──────── Package
                  └────────────── Nominal Supply Voltage
             └─────────────────── Nominal Threshold Voltage
        └──────────────────────── Functionality
  └─────────────────────────────── Family
```

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)[1]

	TPS3806J20, TPS3806I33	UNIT
Supply voltage, V$_{DD}$[2]	7	V
All other pins[2]	-0.3 to 7	V
Maximum low-output current, I$_{OL}$	5	mA
Maximum high-output current, I$_{OH}$	-5	mA
Input clamp current, I$_{IK}$ (V$_I$ < 0 or V$_I$ > V$_{DD}$)	±10	mA
Output clamp current, I$_{OK}$ (V$_O$ < 0 or V$_O$ > V$_{DD}$)	±10	mA
Continuous total power dissipation	See Dissipation Rating Table	
Operating free-air temperature range, T$_A$	-40 to +85	°C
Storage temperature range, T$_{stg}$	-65 to +150	°C
Soldering temperature	+260	°C

(1) Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltage values are with respect to GND. For reliable operation, the device must not be continuously operated at 7 V for more than t = 1000 h.

DISSIPATION RATING TABLE

PACKAGE	T$_A$ < 25°C	DERATING FACTOR ABOVE T$_A$ = 25°C	T$_A$ = 70°C POWER RATING	T$_A$ = 85°C POWER RATING
DBV	437 mW	3.5 mW/°C	280 mW	227 mW

RECOMMENDED OPERATING CONDITIONS

		MIN	MAX	UNIT
Supply voltage, V_{DD}		1.3	6	V
Input voltage, V_I		0	V_{DD} + 0.3	V
Operating free-air temperature range, T_A		-40	+85	°C

ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{OL}	Low-level output voltage		V_{DD} = 1.5 V, I_{OL} = 1 mA			0.3	V
			V_{DD} = 3.3 V, I_{OL} = 2 mA				
			V_{DD} = 6 V, I_{OL} = 3 mA				
	Power-up reset voltage[1]		V_{DD} ≥ 0.8 V, I_{OL} = 50 µA			0.2	V
V_{IT}	Negative-going input threshold voltage[2]	LSENSE	T_A = +25°C	1.198	1.207	1.216	V
		TPS3806J20		1.787	1.8	1.813	
		TPS3806I33		2.978	3.0	3.022	
		LSENSE	T_A = 0°C to +70°C	1.188	1.207	1.226	V
		TPS3806J20		1.772	1.8	1.828	
		TPS3806I33		2.952	3.0	3.048	
		LSENSE	T_A = -40°C to +85°C	1.183	1.207	1.231	V
		TPS3806J20		1.764	1.8	1.836	
		TPS3806I33		2.94	3.0	3.06	
V_{hys}	Hysteresis		1.2 V < V_{IT} < 2.5 V		60		mV
			2.5 V < V_{IT} < 3.5 V		90		
I_I	Input current	LSENSE, HSENSE		-25		25	nA
I_{OH}	High-level output current		V_{DD} = V_{IT} + 0.2 V, V_{OH} = V_{DD}			300	nA
I_{DD}	Supply current		V_{DD} = 3.3 V, Output unconnected		3	5	µA
			V_{DD} = 6 V, Output unconnected		4	6	
C_i	Input capacitance		V_I = 0 V to V_{DD}		1		pF

(1) The lowest supply voltage at which $\overline{RESET}$ becomes active. $t_{r,VDD}$ ≥ 15 µs/V
(2) To ensure best stability of the threshold voltage, place a bypass capacitor (ceramic, 0.1 µF) near the supply terminals.

SWITCHING CHARACTERISTICS

at R_L = 1 MΩ, C_L = 50 pF, T_A = -40°C to +85°C

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PHL}	Propagation (delay) time, high-to-low-level output	V_{DD} to $\overline{RESET}$ delay	V_{IH} = 1.05 x V_{IT}, V_{IL} = 0.95 x V_{IT}		5	100	µs
		LSENSE to $\overline{RSTSENSE}$ delay					
t_{PLH}	Propagation (delay) time, low-to-high-level output	V_{DD} to $\overline{RESET}$ delay			5	100	µs
		HSENSE to $\overline{RSTSENSE}$ delay					

TIMING REQUIREMENTS

at R_L = 1 MΩ, C_L = 50 pF, T_A = -40°C to +85°C

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_w	Pulse width	At V_{DD}	V_{IH} = 1.05 x V_{IT}, V_{IL} = 0.95 x V_{IT}	5.5			µs
		At SENSE					

= Undefined
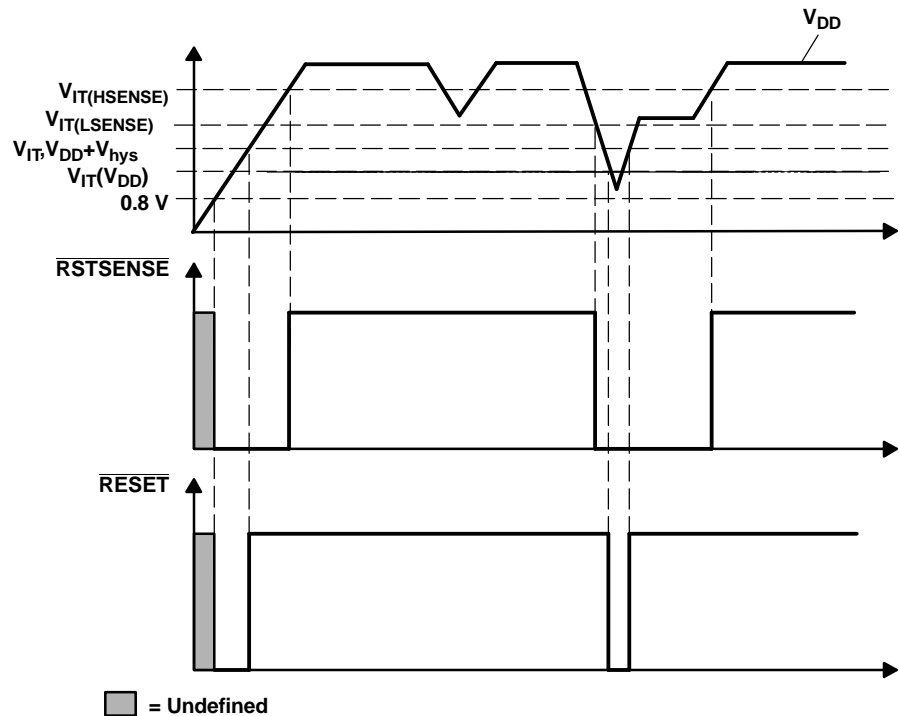
Table 1. TERMINAL FUNCTIONS

TERMINAL		I/O	DESCRIPTION
NAME	NO.		
GND	2	I	Ground
HSENSE	6	I	Adjustable hysteresis input
LSENSE	5	I	Adjustable sense input
$\overline{RESET}$	3	O	Active-low open drain reset output (from V_{DD})
$\overline{RSTSENSE}$	1	O	Active-low open-drain reset output (from LSENSE)
V_{DD}	4	I	Input supply voltage and fixed sense input

FUNCTION/TRUTH TABLE

TPS3806			
$V_{DD} > V_{IT}$	$\overline{RESET}$	LSENSE > V_{IT}	$\overline{RSTSENSE}$
0	L	0	L
1	H	1	H

FUNCTIONAL BLOCK DIAGRAM
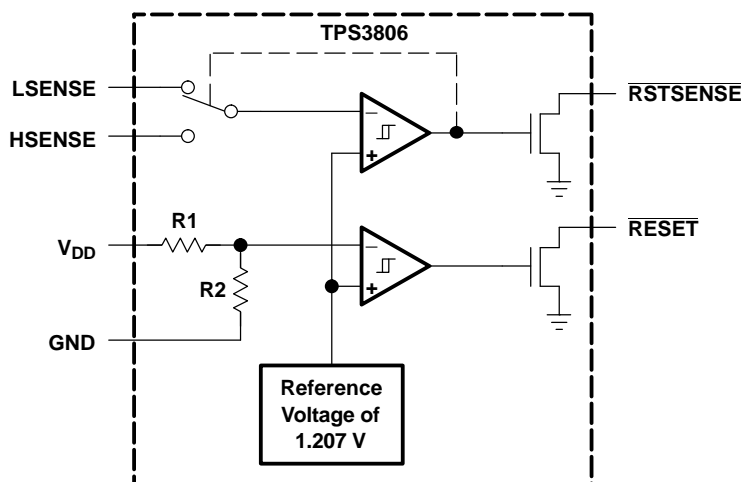
Detailed Description

Operation

The TPS3806 is used for monitoring battery voltage and asserting $\overline{\text{RESET}}$ when a battery gets discharged below a certain threshold voltage. The battery voltage is monitored by a comparator via an external resistor divider. When the voltage at the LSENSE input drops below the internal reference voltage the $\overline{\text{RSTSENSE}}$ output pulls low. The output remains low until the battery is replaced, or recharged above a second higher trip-point, set at HSENSE. A second voltage can be monitored at V_{DD}. The independent $\overline{\text{RESET}}$ output pulls low when the voltage at V_{DD} drops below the fixed threshold voltage. Because the TPS3806 outputs are open-drain MOSFETs, most applications may require a pull-up resistor.

Programming the Threshold Voltage Levels

The low-voltage threshold at LSENSE is calculated according to Equation 1:

$$V_{(LSENSE)} = V_{ref}\left(\frac{R1 + R2 + R3}{R2 + R3}\right)$$

(1)

where V_{ref} = 1.207 V

The high-voltage threshold at HSENSE is calculated as shown in Equation 2:

$$V_{(HSENSE)} = V_{ref}\left(\frac{R1 + R2 + R3}{R3}\right)$$

(2)

where V_{ref} = 1.207 V

To minimize battery current draw it is recommended to use 1-MΩ as the total resistor value $R_{(tot)}$, with $R_{(tot)}$ = R1 + R2 + R3.

TYPICAL CHARACTERISTICS

SUPPLY CURRENT
vs
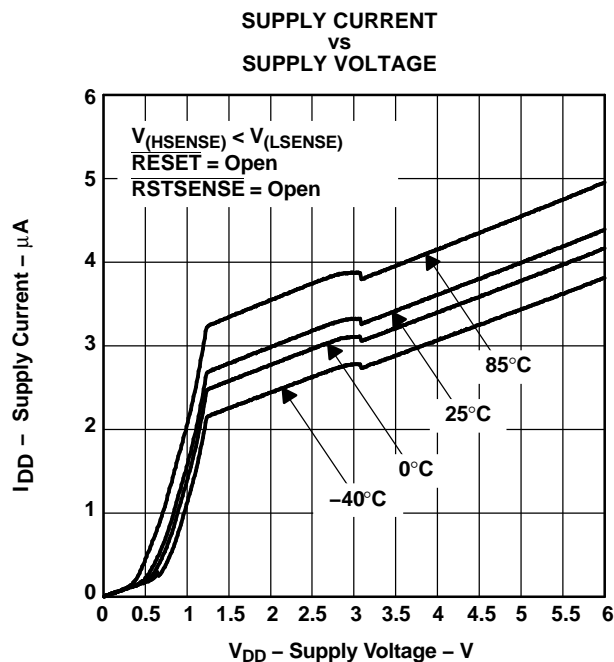**SUPPLY VOLTAGE**

Figure 1.

LOW-LEVEL OUTPUT VOLTAGE
vs
LOW-LEVEL OUTPUT CURRENT

Figure 2.

LOW-LEVEL OUTPUT VOLTAGE
vs
LOW-LEVEL OUTPUT CURRENT

Figure 3.

LOW-LEVEL OUTPUT VOLTAGE
vs
LOW-LEVEL OUTPUT CURRENT
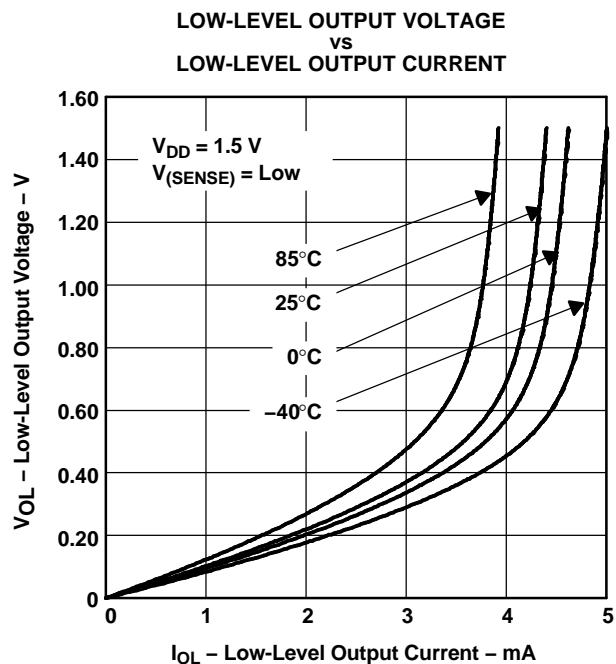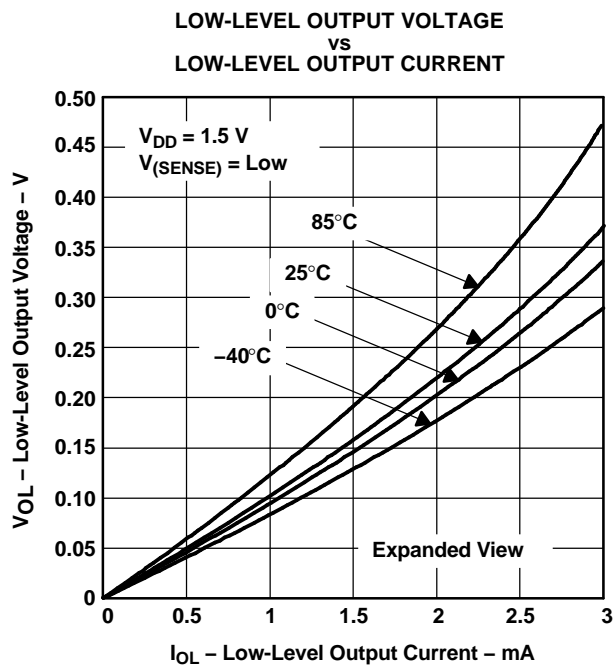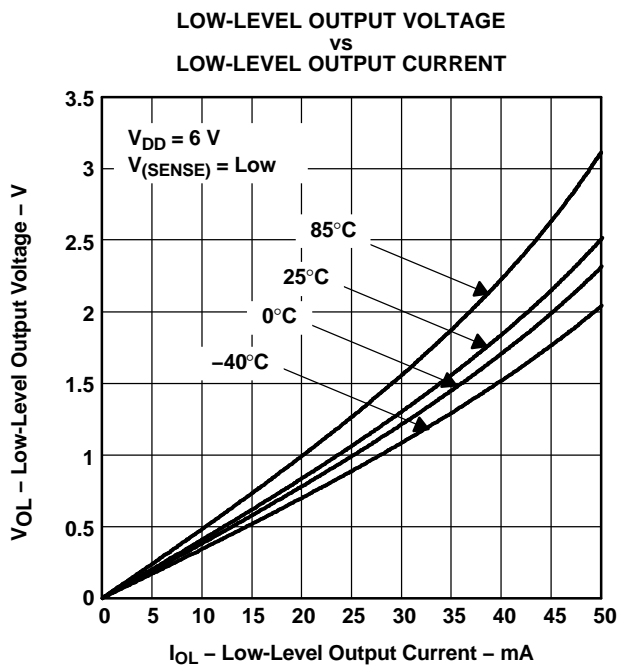
Figure 4.

TYPICAL CHARACTERISTICS (continued)

LOW-LEVEL OUTPUT VOLTAGE
vs
LOW-LEVEL OUTPUT CURRENT

Figure 5.

NORMALIZED INPUT THRESHOLD VOLTAGE
vs
FREE-AIR TEMPERATURE AT V$_{DD}$

Figure 6.

MINIMUM PULSE DURATION AT V$_{DD}$
vs
V$_{DD}$ THRESHOLD OVERDRIVE VOLTAGE

Figure 7.

MINIMUM PULSE DURATION AT LSENSE
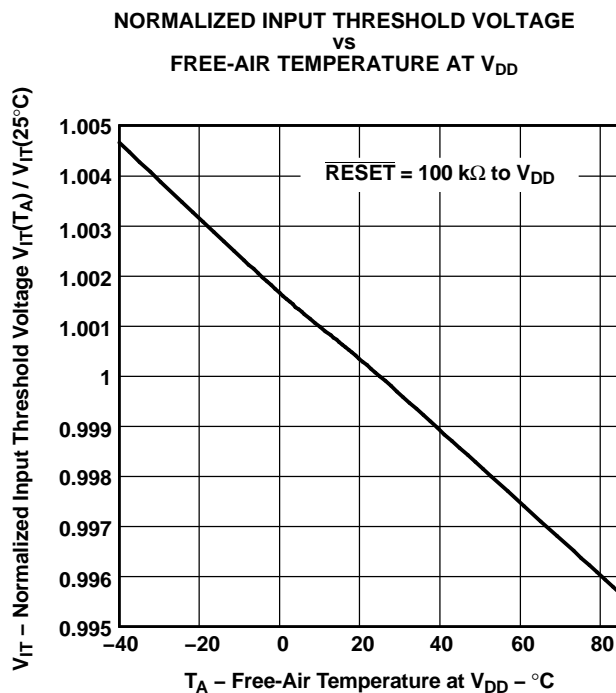**vs**
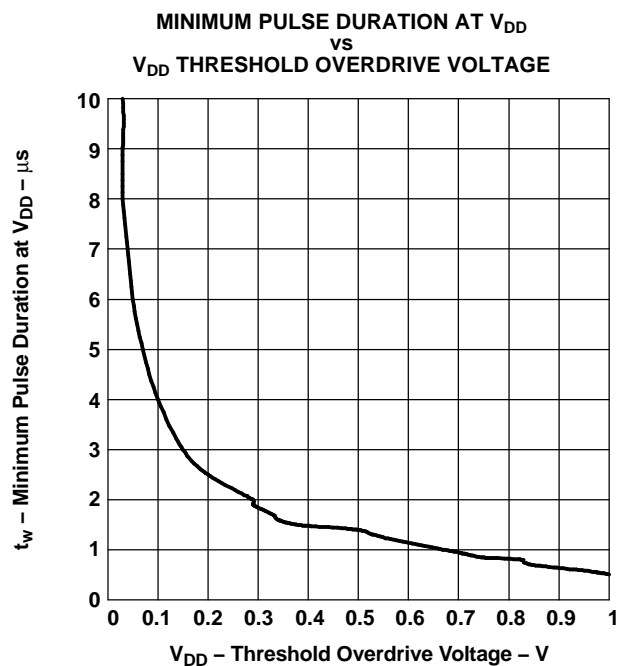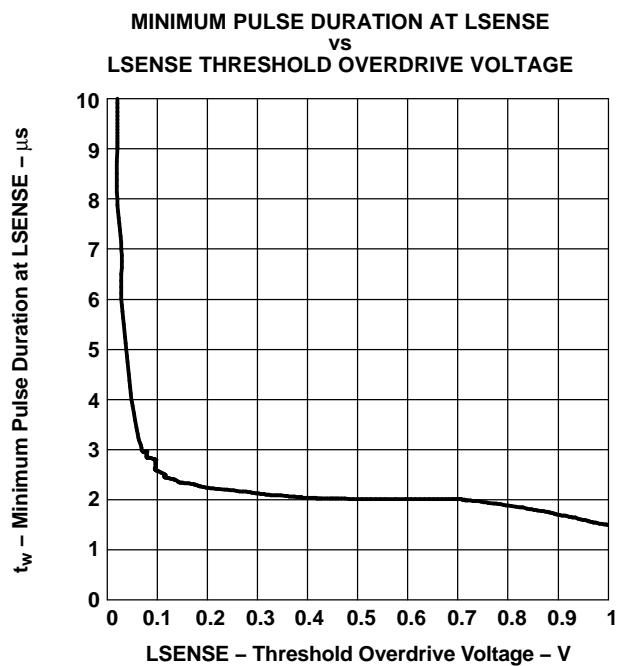**LSENSE THRESHOLD OVERDRIVE VOLTAGE**
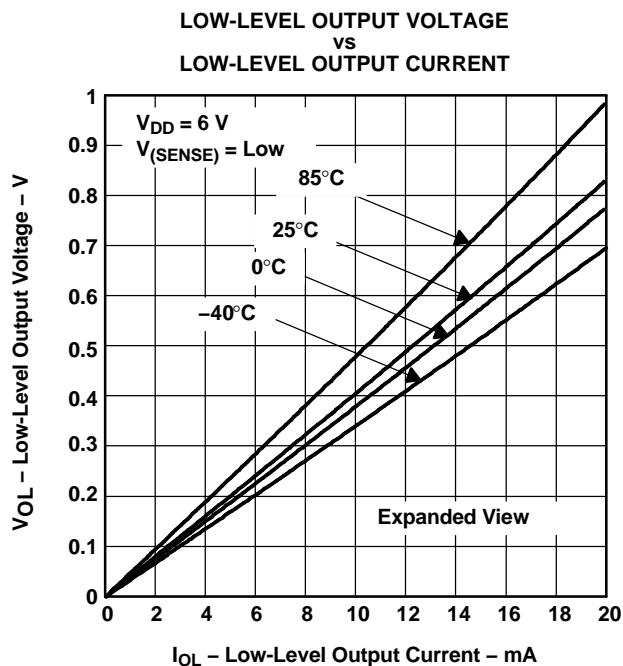
Figure 8.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
TPS3806I33DBVR	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PGPI	Samples
TPS3806I33DBVRG4	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PGPI	Samples
TPS3806I33DBVT	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PGPI	Samples
TPS3806I33DBVTG4	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PGPI	Samples
TPS3806J20DBVR	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PGQI	Samples
TPS3806J20DBVRG4	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PGQI	Samples
TPS3806J20DBVT	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PGQI	Samples
TPS3806J20DBVTG4	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PGQI	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

---

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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OTHER QUALIFIED VERSIONS OF TPS3806I33 :

- Automotive: TPS3806I33-Q1

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

![Texas Instruments logo] **PACKAGE MATERIALS INFORMATION**

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS3806I33DBVR	SOT-23	DBV	6	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS3806I33DBVR	SOT-23	DBV	6	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3806I33DBVT	SOT-23	DBV	6	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3806I33DBVT	SOT-23	DBV	6	250	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS3806J20DBVR	SOT-23	DBV	6	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3806J20DBVT	SOT-23	DBV	6	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3

![Texas Instruments logo]

PACKAGE MATERIALS INFORMATION

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS3806I33DBVR	SOT-23	DBV	6	3000	203.0	203.0	35.0
TPS3806I33DBVR	SOT-23	DBV	6	3000	180.0	180.0	18.0
TPS3806I33DBVT	SOT-23	DBV	6	250	180.0	180.0	18.0
TPS3806I33DBVT	SOT-23	DBV	6	250	203.0	203.0	35.0
TPS3806J20DBVR	SOT-23	DBV	6	3000	180.0	180.0	18.0
TPS3806J20DBVT	SOT-23	DBV	6	250	180.0	180.0	18.0

DBV (R−PDSO−G6)   PLASTIC SMALL−OUTLINE PACKAGE
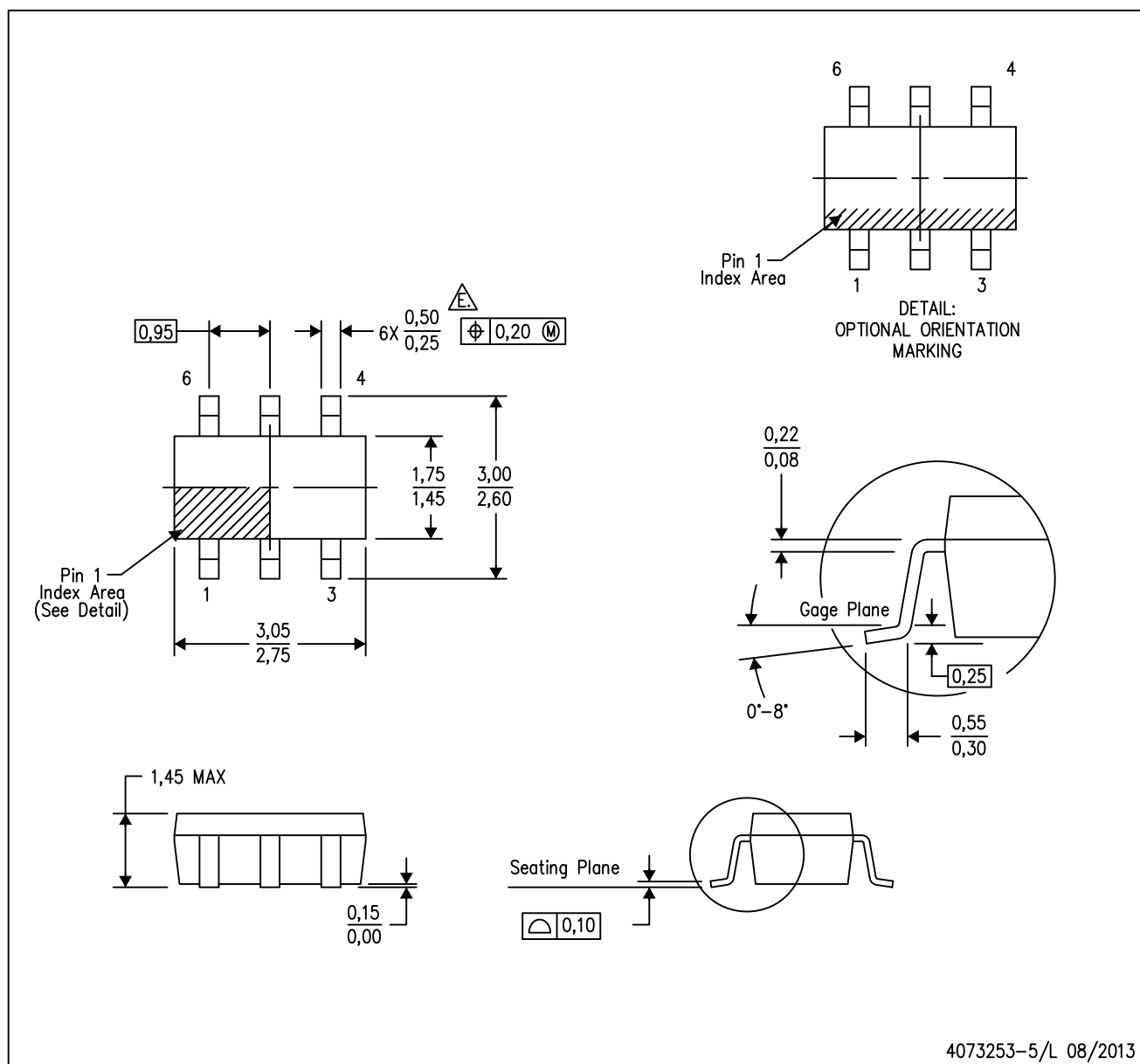
6   4

Pin 1
Index Area

DETAIL:
OPTIONAL ORIENTATION
MARKING

0,95   6X 0,50 / 0,25   ⊕ 0,20 Ⓜ   Ⓔ

6   4

1,75 / 1,45   3,00 / 2,60

Pin 1
Index Area
(See Detail)   1   3

3,05 / 2,75

0,22 / 0,08

Gage Plane

0°−8°   0,25   0,55 / 0,30

1,45 MAX

0,15 / 0,00

Seating Plane   0,10

4073253−5/L 08/2013
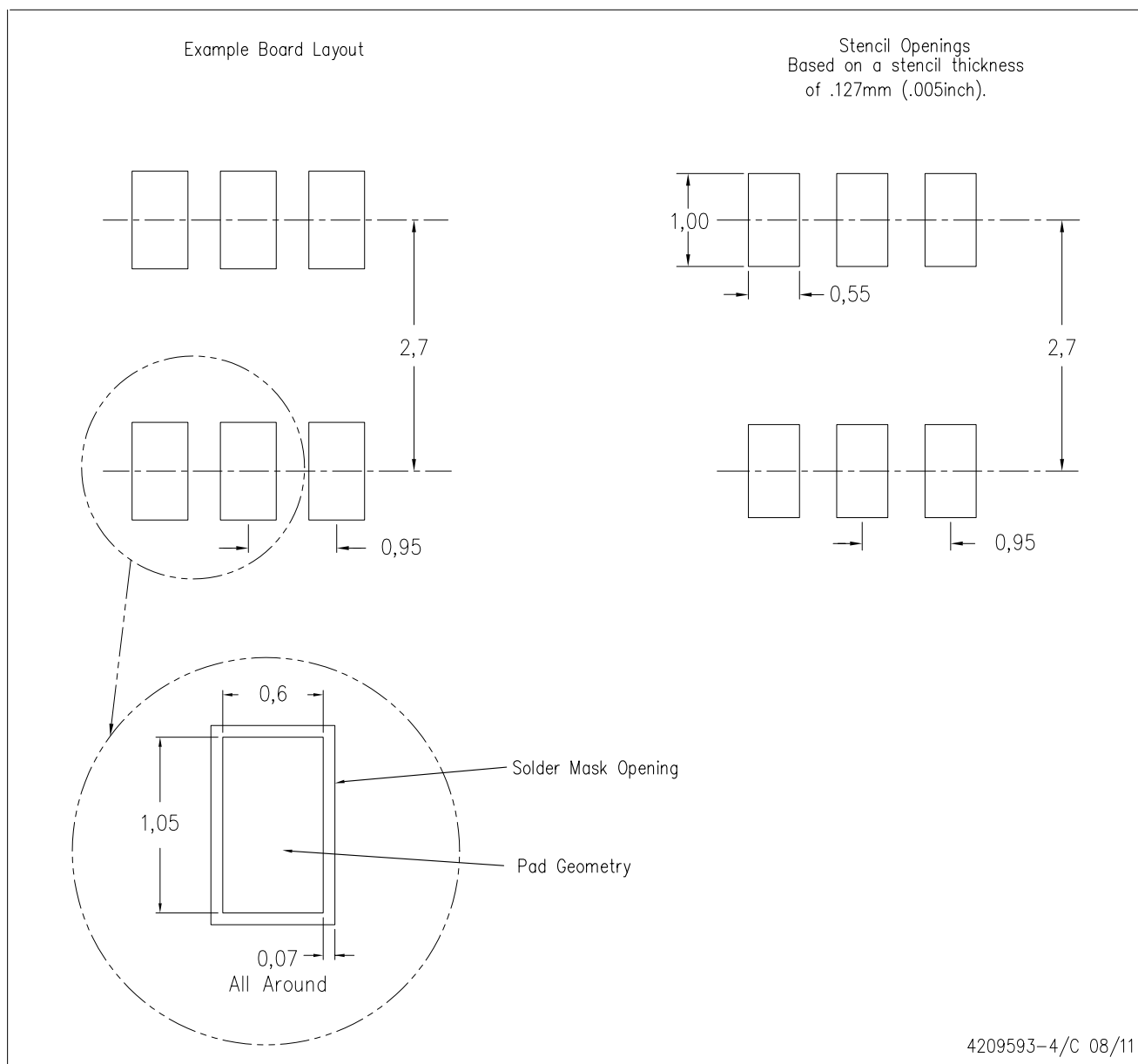
NOTES: A. All linear dimensions are in millimeters.
         B. This drawing is subject to change without notice.
         C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
         D. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
         Ⓔ Falls within JEDEC MO−178 Variation AB, except minimum lead width.

DBV (R−PDSO−G6)   PLASTIC SMALL OUTLINE

Example Board Layout

Stencil Openings
Based on a stencil thickness
of .127mm (.005inch).

1,00

0,55

2,7

2,7

0,95

0,95

0,6

Solder Mask Opening

1,05

Pad Geometry

0,07
All Around

4209593−4/C 08/11

NOTES: A.   All linear dimensions are in millimeters.
         B.   This drawing is subject to change without notice.
         C.   Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
         D.   Publication IPC−7351 is recommended for alternate designs.
         E.   Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
              contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric
              metal load solder paste. Refer to IPC−7525 for other stencil recommendations.

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